

Product Summary

BV_{DSS}	$R_{DS(ON)}$	I_D $T_A = +25^\circ\text{C}$
60V	$2\Omega @ V_{GS} = 4V$	320mA
	$2.5\Omega @ V_{GS} = 2.5V$	50mA

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

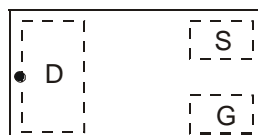
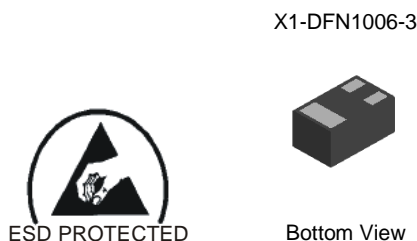
- DC-DC Converters
- Power Management Functions
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.

Features and Benefits

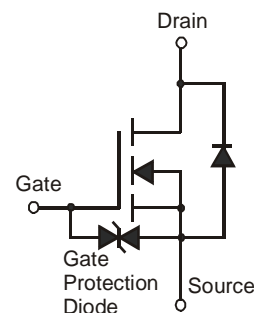
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.001 grams (Approximate)



Top View
Pin-Out





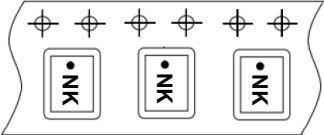
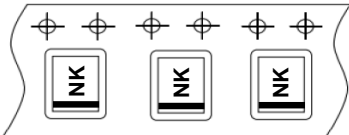

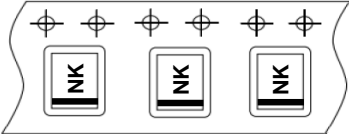
Equivalent Circuit

Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DMN62D0LFB-7	NK	7	8	3,000
DMN62D0LFB-7B	NK	7	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

DMN62D0LFB-7	<div style="display: flex; justify-content: space-around; align-items: flex-start;"> <div style="text-align: center;">  <p>Top View Dot Denotes Drain Side</p> </div> <div style="text-align: center;"> <p>From date code 1527 (YYWW), this changes to:</p>  <p>Top View Bar Denotes Gate and Source Side</p> </div> </div> <div style="display: flex; justify-content: space-around; align-items: center; margin-top: 10px;">   </div>
DMN62D0LFB-7B	<div style="text-align: center; margin-bottom: 10px;">  <p>Top View Bar Denotes Gate and Source Side</p> </div> <div style="text-align: center; margin-bottom: 10px;"> <p>NK = Part Marking Code</p> </div> <div style="text-align: center;">  </div>

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	60	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 5) V _{GS} = 4.0V	Steady State	T _A = +25°C T _A = +70°C	I _D	320 75	mA
Pulsed Drain Current (Note 6)			I _{DM}	1	A

Thermal Characteristics

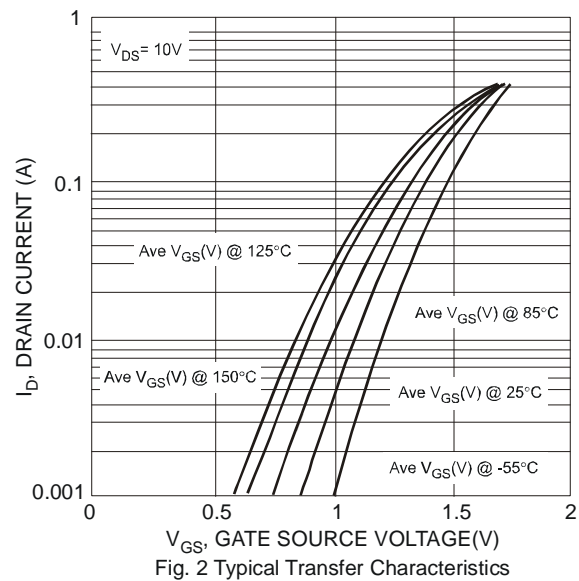
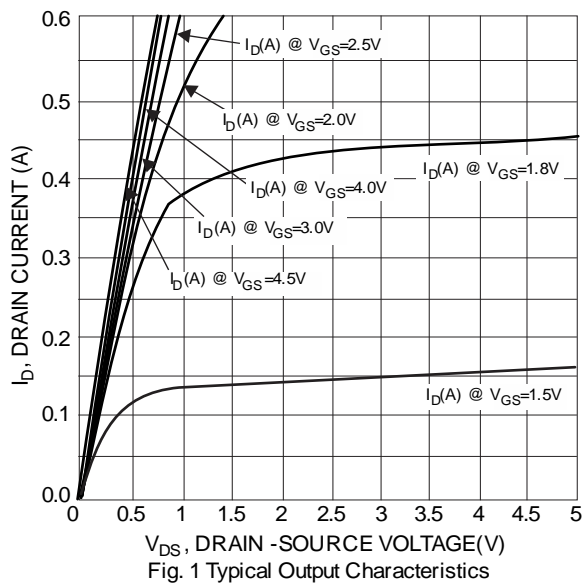
Characteristic	Symbol	Max	Unit
Power Dissipation (Note 5)	P _D	0.5	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	R _{θJA}	258	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

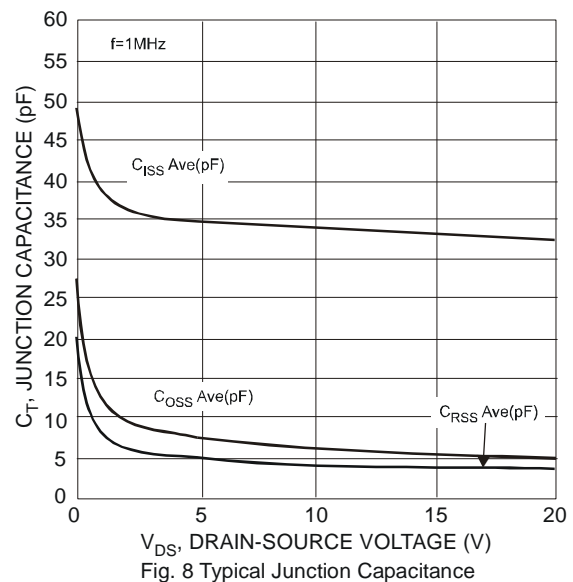
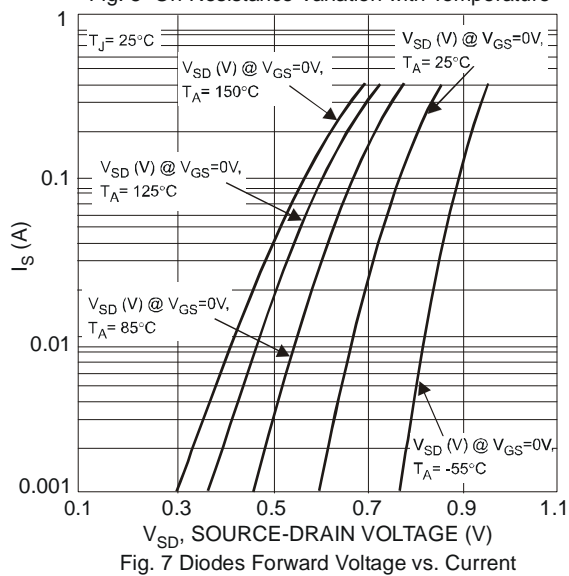
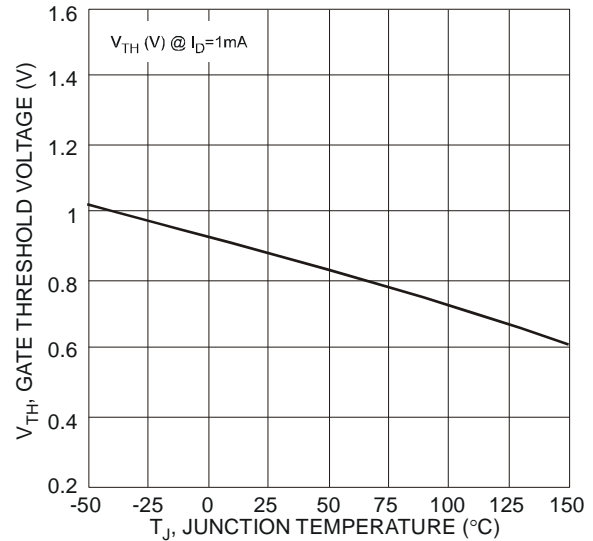
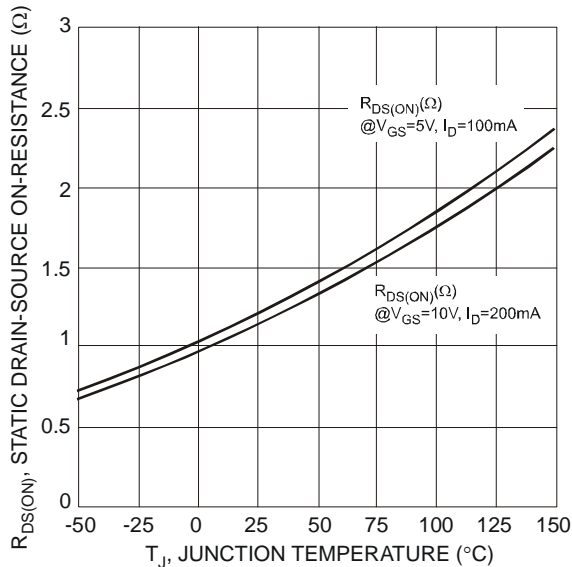
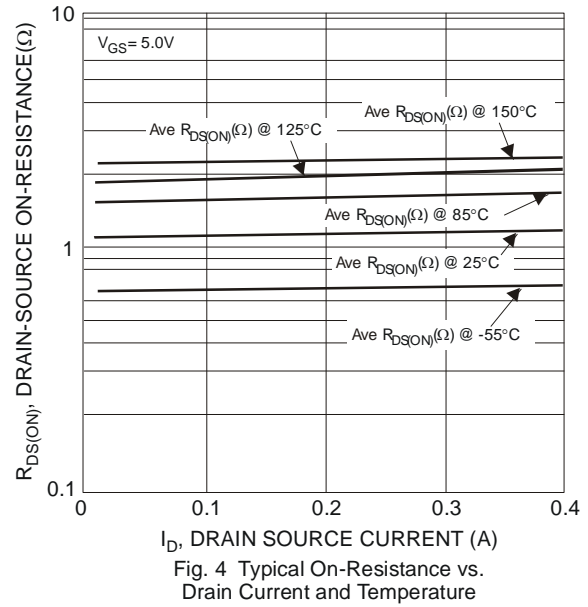
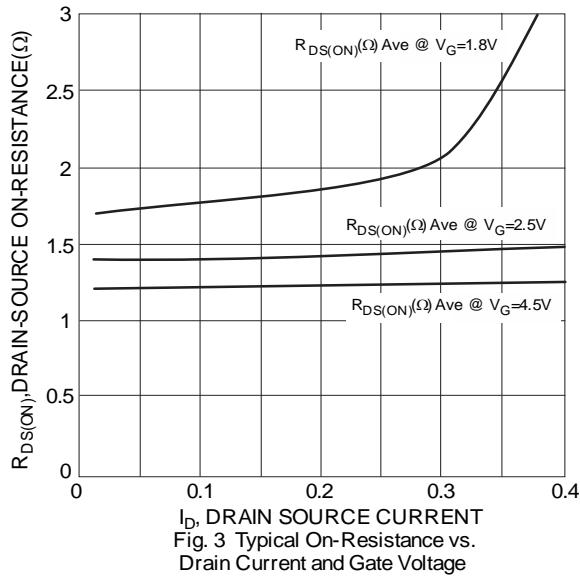
Notes: 5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
 6. Repetitive rating, pulse width limited by junction temperature.

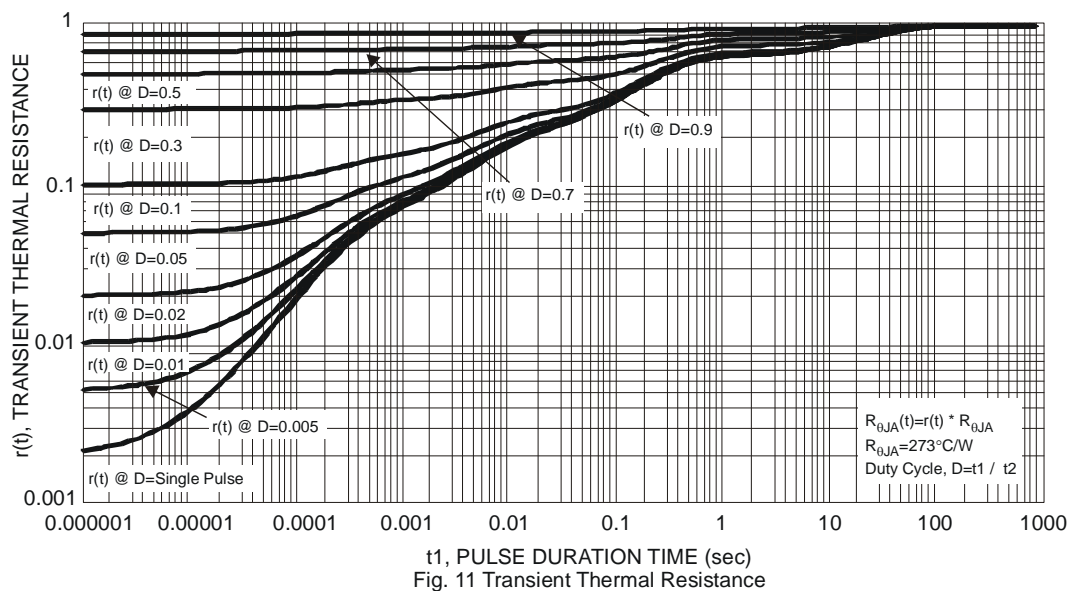
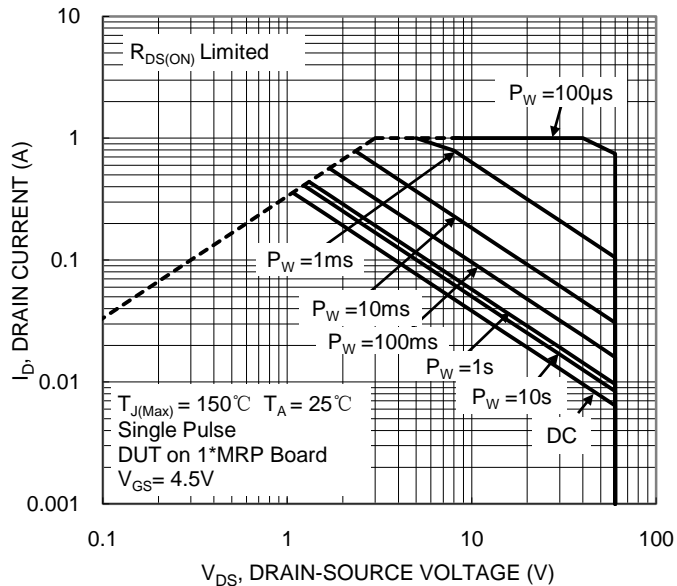
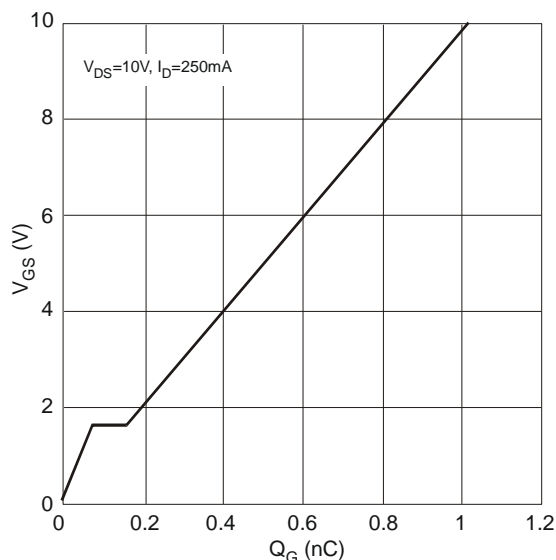
Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise stated.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	60	-	-	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	-	1.0	μA	V _{DS} = 60V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	V _{GS} = ±5V, V _{DS} = 0V
		-	-	±500	nA	V _{GS} = ±10V, V _{DS} = 0V
		-	-	±2.0	μA	V _{GS} = ±15V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.6	-	1.0	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	-	1.3	2	Ω	V _{GS} = 4V, I _D = 100mA
		-	1.5	2.5		V _{GS} = 2.5V, I _D = 50mA
		-	1.9	3		V _{GS} = 1.8V, I _D = 50mA
		-	2.6	-		V _{GS} = 1.5V, I _D = 10mA
Forward Transfer Admittance	Y _{fs}	-	0.8	-	S	V _{DS} = 10V, I _D = 200mA
Diode Forward Voltage	V _{SD}	-	0.9	1.3	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	-	32	64	pF	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	4.4	9		
Reverse Transfer Capacitance	C _{rss}	-	2.9	6		
Gate Resistance	R _g	-	126	250	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge	Q _g	-	0.45	0.9	nC	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 250mA
Gate-Source Charge	Q _{gs}	-	0.08	0.2		
Gate-Drain Charge	Q _{gd}	-	0.08	0.2		
Turn-On Delay Time	t _{D(ON)}	-	3.4	10	ns	V _{GS} = 10V, V _{DS} = 30V, R _L = 150Ω, R _g = 25Ω, I _D = 200mA
Turn-On Rise Time	t _r	-	3.4	10	ns	
Turn-Off Delay Time	t _{D(OFF)}	-	26.4	45	ns	
Turn-Off Fall Time	t _f	-	16.3	30	ns	

Notes: 7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to production testing.



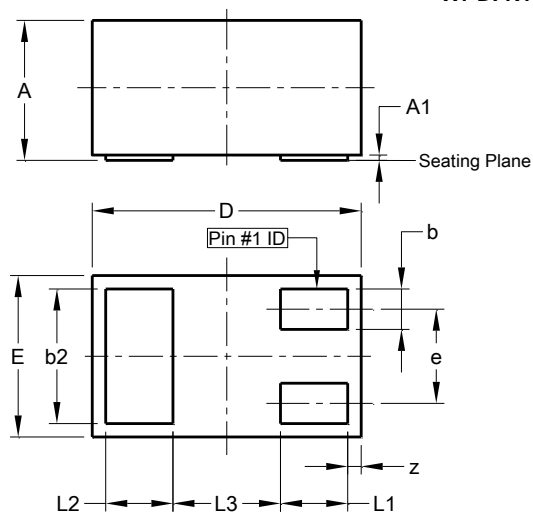




Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1006-3

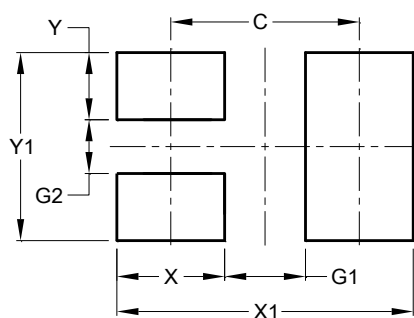


X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1006-3



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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